

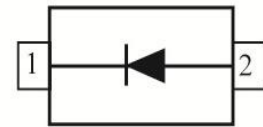
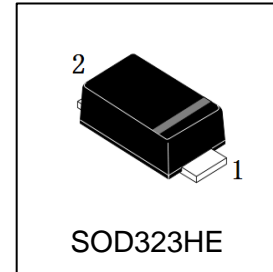
# LMBR140ET1G

## S-LMBR140ET1G

Schottky Barrier Diode

### 1. FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.
- Low power loss,high efficiency.
- For use in low voltage high frequency inverters,free wheeling,and polarity protection applications.
- Guardring for over voltage protection.
- High temperature soldering guaranteed:260°C/10 seconds at terminals.



### 2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
LMBR140ET1G	14	3000/Tape&Reel
S-LMBR140ET1G	14	3000/Tape&Reel

### 3. MAXIMUM RATINGS(Ta = 25°C)

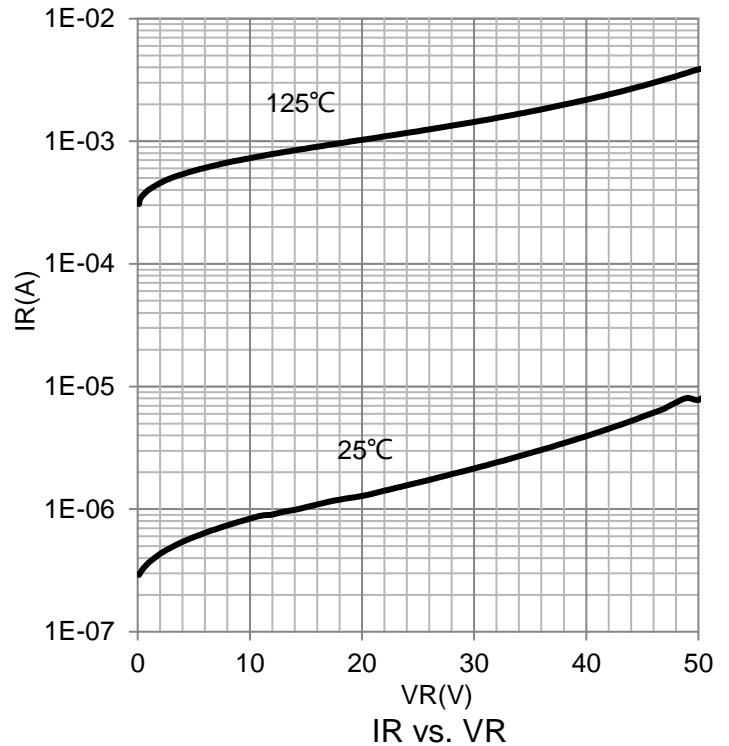
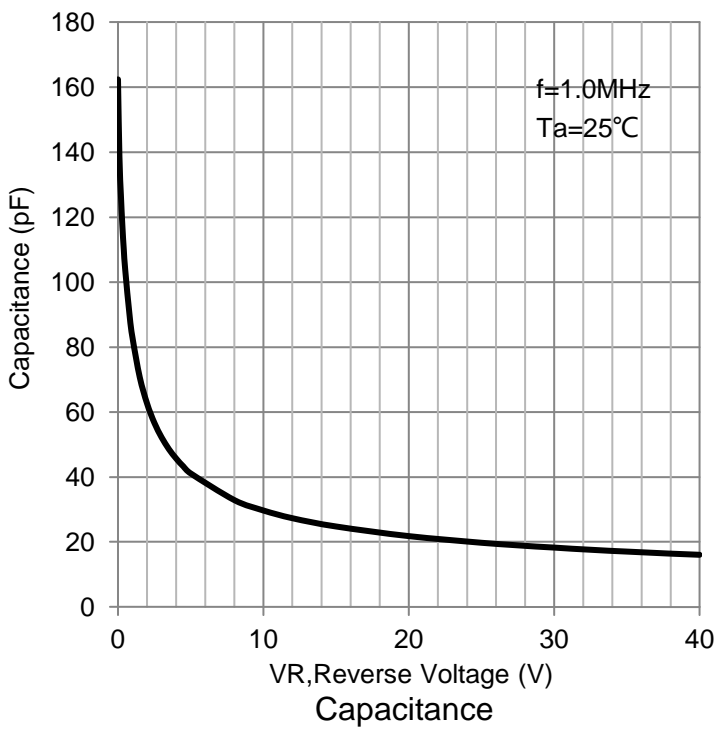
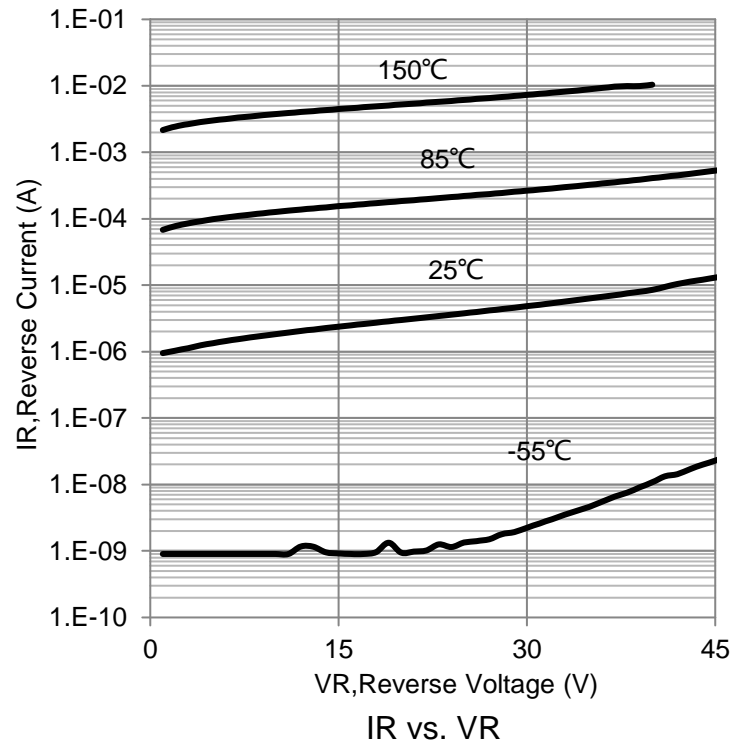
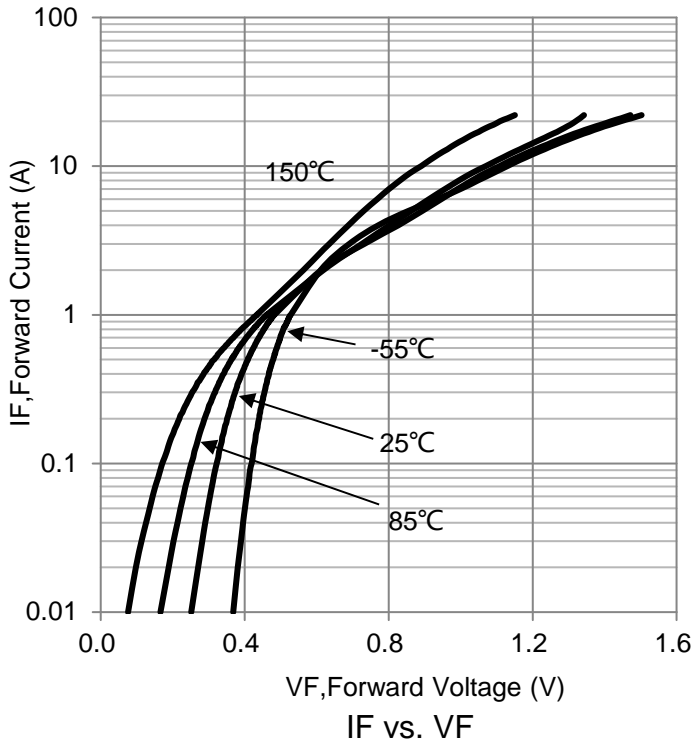
Parameter	Symbol	Limits	Unit
Maximum repetitive peak reverse voltage	VRRM	40	V
Maximum RMS voltage	VRMS	28	V
Maximum DC blocking voltage	VDC	40	V
Maximum average forward rectified current at TC = 75°C	IF(AV)	1	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	IFSM	22	A
Typical thermal resistance (Note 1)	RθJA	220	°C/W
	RθJL	50	
Operating junction temperature range	TJ	-55 ~ +125	°C
storage temperature range	TSTG	-55 ~ +150	°C

Note: 1. 8.0mm<sup>2</sup> (.013mm thick) land areas

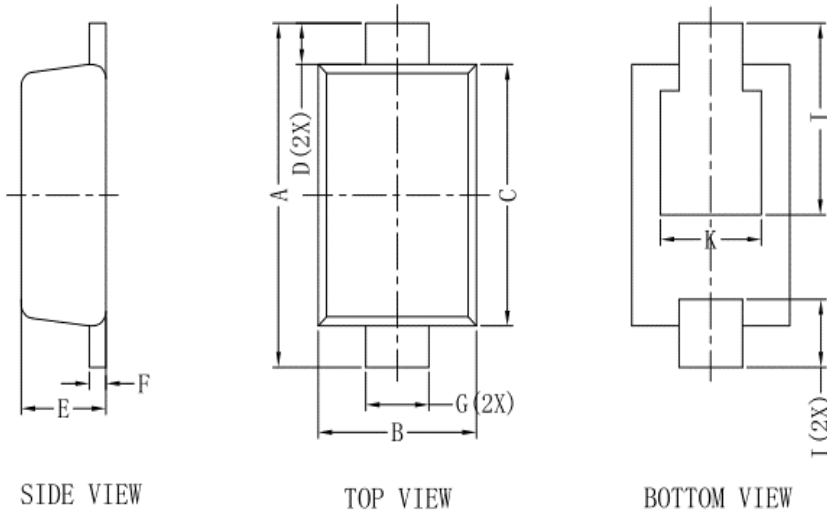
**4. ELECTRICAL CHARACTERISTICS (Ta= 25°C)**

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Maximum instantaneous forward (IF =0.7 A, TJ = 25°C)	VF	-	-	0.48	V
(IF = 1.0 A, TJ = 25°C)		-	-	0.55	
Maximum DC reverse current at rated DC blocking voltage TA = 25°C	IR	-	5	30	uA
TJ = 125°C		-	2.5	10	mA
Typical junction capacitance at 4.0V, 1MHz	CJ	-	50	-	pF

**5. ELECTRICAL CHARACTERISTICS CURVES**



**6.OUTLINE AND DIMENSIONS**



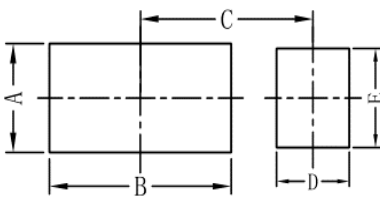
SOD323HE			
DIM	MIN	MAX	Typ.
A	2.30	2.70	2.55
B	1.20	1.35	1.25
C	1.75	1.95	1.90
D	-	-	0.30
E	0.55	0.75	0.67
F	0.10	0.20	0.15
G	0.45	0.65	0.50
I	0.40	0.70	0.50
J	1.15	1.55	1.40
K	-	-	0.80
All Dimensions in mm			

**GENERAL NOTES**

- 1.Top package surface finish  $Ra0.4\pm0.2\mu m$
- 2.Bottom package surface finish  $Ra0.7\pm0.2\mu m$

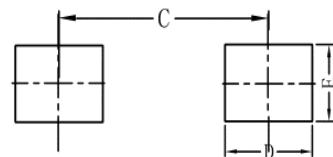
**7.SOLDERING FOOTPRINT**

**RECOMMENDED PAD**



SOD323HE	
DIM	(mm)
A	1.1
B	2.0
C	1.9
D	0.8
E	1.1

**COMPATIBLE PAD**



SOD323HE	
DIM	(mm)
D	1.0
E	0.8
C	2.4

单击下面可查看定价，库存，交付和生命周期等信息

[>>LRC\(乐山无线电\)](#)